Co-packaged Photonics Intelligence 2026 Model



Overview

In 2026, that is finally changing. Co-Packaged Optics (CPO) — putting a silicon photonics engine directly inside the same package as a network switch or GPU ASIC — has moved from research papers and OFC demos into the shipping roadmaps of NVIDIA, Broadcom, Marvell, TSMC . In 2026, that is finally changing. According to LightCounting, sales of lasers and photonic integrated circuits for optical transceivers are expected to grow from $2. Read on to learn key CPO trends shaping AI systems in 2026 and the challenges designers will need to. 2026 will mark the year when co-packaged optics (CPO), a form of optoelectronic integration, enters the full-scale mass production and practical roll-out phase. As power consumption continues to surge with the rapid expansion of AI data centers, expectations are high that CPO will dramatically. Passage ® interconnects and Guide ® light engines scale networking for AI supercomputers. Complete photonics roadmap from NPO and OBO to 2D and 3D CPO and 3D Interposers. Edgeless I/O architecture enabling unlimited bandwidth scaling. Very Large Scale Photonics technology.



© 2026 CJC FIBRE CONSULTANTS - All rights reserved

Article Content

Co-Packaged Optics 2026

In 2026, that is finally changing. Co-Packaged Optics (CPO) — putting a silicon photonics engine directly inside the same package as a network switch or GPU ASIC — has moved from research

Five Key Trends of Co-Packaged Optics (CPO) in 2026

Meeting market expectations and building confidence in co-packaged optics will require more than performance demonstrations. CPO adoption

Co-Packaged Optics Gain Traction in Data Centers

Along the timeline of adoption, 2026 is expected to be a transitional period in which CPO technology becomes increasingly incorporated into switches for hyperscalers while conventional

Lightmatter®

Lightmatter InterConnect 2026 Keynote Presentation InterConnect 2026 keynote: photonic interconnects, co-packaged optics, and the future of AI. Explore how next-generation networking

Silicon Photonics & Co-Packaged Optics: 2026 Analysis

Why co-packaged optics and silicon photonics are reshaping AI data centers in 2026 — the bandwidth wall, power math, incumbents, and what it means.

Industry insight: photonics to scale AI data centers

By analyzing their integration at the package, rack, and network levels, we highlight how photonics can overcome the limitations of traditional electronic solutions, paving the way for the next...

Co-Packaged Optics (CPO) 2026-2036: Technologies, Market, and

The report is based on extensive research and interviews with industry experts and provides valuable insights for anyone interested in gaining a strategic understanding of Co-Packaged Optics'' role in

Where co-packaged optics (CPO) technology stands in

Find out CPO''s 2025 scorecard and what lies ahead for this optical interconnect technology in 2026 and beyond.

Silicon Photonics Networking for Agentic AI | NVIDIA

© 2026 CJC FIBRE CONSULTANTS - All rights reserved

NVIDIA co-packaged optics with silicon photonics deliver 5x power efficiency and 10x resiliency, enabling scalable, high-performance networking for agentic AI.

Co-Packaged Optics: powering the next wave of AI

This event will bring together leading experts to explore how photonics and advanced semiconductor technologies are converging to meet the growing

Co-Packaged Optics Market Size, Growth & Trends, 2031

Co-packaged optics market to grow from USD 161.43M in 2026 to USD 748.62M by 2031, driven by AI/ML bandwidth, hyperscale data centers, and thermal-efficient switches.

PwC_Semiconductor and Beyond_2026

At PwC, we have worked alongside semiconductor leaders through multiple industry shifts, helping clients adapt to evolving market conditions, enhance supply chains and drive long-term sustainable

MarketsandMarkets

Revenue Impact Firm - MarketsandMarkets offers market research reports and quantified B2B research on 30000 high growth emerging opportunities to over 10000 clients worldwide. Get detailed insights

NVIDIA Kicks Off the Next Generation of AI With Rubin

NVIDIA Spectrum-6 Ethernet is the next generation of Ethernet for AI networking, built to scale Rubin-based AI factories with higher efficiency and greater resilience, and enabled by 200G

TSMC Coupe: An Underrated Optical Platform-Electronics Headlines

TSMC''s COUPE platform is less of a branded, finished switch SKU and more of a silicon photonics integration platform and technical service. It integrates photonic integrated circuits with

Ansys | Engineering Simulation Software

Ansys 2026 R1: Engineering Solutions from Systems to Silicon Ansys, part of Synopsys empowers engineers to design smarter products, reduce physical

© 2026 CJC FIBRE CONSULTANTS - All rights reserved

Contact Us

Continue your research online:

Website: https://cjcconsultants.co.za
Technical inquiry: https://cjcconsultants.co.za/contact.html

This document is for preliminary research. Verify specifications against current standards, product documentation and project requirements.

© 2026 CJC FIBRE CONSULTANTS - All rights reserved